

# XN8161-B200

## Technical Specifications

Form Factor	8U Rackmount	Additional GbE Controller	Intel® i350: 2 RJ45 (1GbE)
Dimension	930 x 448 x 353.6mm (36.6" x 17.6" x 13.9")	BMC Controller	ASPEED AST2600
Button	Power button w/LED, reset button, NMI button, UID button	IPMI Dedicated GLAN	• 1 Realtek RTL8211F for dedicated management GLAN
LED	System fault LED, hard drive activity LED	Controller	ASPEED AST2600
I/O Port	<ul style="list-style-type: none"> <li>2 RJ45 (1GbE) by Intel® i350, share with rear I/O</li> <li>1 Dedicated IPMI, shares with rear I/O</li> <li>4 Type-A(USB3.2 Gen1)</li> <li>1 DB15(VGA)</li> </ul>	VRAM	DDR4 512MB
Front Side Drive Bay	<ul style="list-style-type: none"> <li>8 Hot-swap 2.5" NVMe (PCIe5.0 x 4) drive bays from PCIe switch</li> <li>2 Hot-swap 2.5" NVMe (PCIe5.0 x 4)/SATA drive bays form CPU</li> </ul>	UID Button/ LED	1 UID button
Internal Side	<ul style="list-style-type: none"> <li>1 M-key (PCIe3.0 x 2 or SATA 6Gb/s), supports 2280/22110 form factor [PCH]</li> <li>1 M-key (PCIe3.0 x 4), supports 2280/22110 form factor [PCH]</li> </ul>	VGA Port	1 DB15 (VGA)
Power Supply Type	6+6 CRPS	USB32 Gen1 Port	2 Type-A (USB32 Gen1)
Output Watt	<ul style="list-style-type: none"> <li>3002.4W @ 220-240Vac input</li> <li>2900W @ 200-220Vac input</li> </ul>	RJ45	<ul style="list-style-type: none"> <li>2 RJ45 (1GbE) by Intel® i350, share with front panel</li> <li>1 Dedicated IPMI shares with front panel</li> </ul>
Efficiency	80-PLUS Titanium	Temperature Monitor	• CPU, MB, card side temperature sensing
AC Input	200-240Vrms, 50/60Hz	Fan	<ul style="list-style-type: none"> <li>Fan tachometer</li> <li>CPU Quiet Fan (allows chassis fan speed auto-adjust by CPU temperature)</li> <li>Fan multi-speed control</li> </ul>
System Fan	<ul style="list-style-type: none"> <li>29 PWM 80 x 80mm fans</li> <li>4 PWM 40 x 40mm fans</li> </ul>		
GPU	NVIDIA® HGX B200 8-GPU with NVIDIA® NVSwitch™		
CPU	Supports 5th and 4th Gen Intel® Xeon® Scalable Processors		
Socket	Dual Socket E (LGA4677)		
Thermal Design Power	Up to 350W		
Chipset	C741		
Supported DIMM Quantity	16+16 DIMM slots (2DPC)		
Max Capacity per DIMM	<ul style="list-style-type: none"> <li>RDIMM: 96GB</li> <li>RDIMM-3DS: 2H-128GB/4H-256GB</li> </ul>		
PCIe x16	<p>Rear:</p> <ul style="list-style-type: none"> <li>8 HHHL PCIe5.0 x 16</li> <li>2 FHHL PCIe5.0 x 16</li> </ul>		

